



承認書

SPECIFICATION FOR APPROVAL

CUSTOMER:

DESCRIPTION:

WIRE WOUND CHIP INDUCTOR

PART NO:

MWI1206UC3N3KST-HF

CUST. PART NO:

REV. NO.

A0

DRAWING		
PREPARED	CHECKED	APPROVED
邹声平	卢嘉良	曾凡强
DATE:	2025/6/9	

CUSTOMER APPROVE

 **德立电子&铭易轩**

东莞市铭易轩电子科技有限公司

DongGuan Ming Yixuan Electronic Technology Co., LTD.

地址: 广东省东莞市大朗镇景泰路20号VV大厦

工厂地址: 广东省惠州市博罗县洲际工业园梅园三路

电话: 13640935893 , 15970768093

网址: <http://www.dgmingyixuan.com>



MODIFY RECORD 变更履历

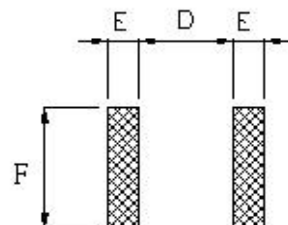
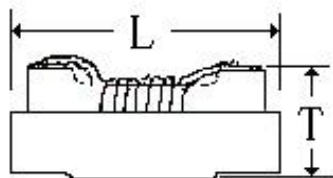
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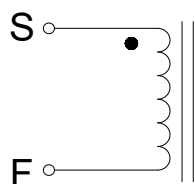
1. SHAPE & DIMENSION (UNIT:mm)



Recommended patterns

L	W	T	E	F	D
3.56 Max.	2.16 Max.	1.52 Max.	1.02 Typ.	1.93 Typ.	1.78 Typ.

2. SCHEMATIC



3. PART NUMBERING SYSTEM

MWI	1206	UC	3N3	K	S	T	-	HF
1	2	3	4	5	6	7		8

- 1 PRODUCT SYMBOL (产品代号)
- 2 DIMENSIONS (规格尺寸)
- 3 MATERIAL (类型)
- 4 INDUCTANCE (电感量)
- 5 TOLERANCE (公差) : G $\pm$ 2%; J $\pm$ 5%; K $\pm$ 10%; M $\pm$ 20%
- 6 TERMINAL (端电极材料): G-金端头; S-锡端头;
- 7 PACKAGING (包装方式): T-编带盘装; B-散装
- 8 E.P. (环保): LF—Lead Free HF—Halogen Free FP—Red Phosphor Free

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4. ELECTRICAL CHARACTERISTICS

No.	Part Number	Inductance	Test Freq	Q	SRF	Rdc	Irms	Tolerance
		(nH)	(MHz)	Min.	(MHz)Min.	(Ω) Max.	(mA) Max.	
1	MWI1206UC3N3KST-HF	3.3	100	20@300MHz	6200	0.07	1000	J,K,M

Test remarks

- (1). All test data is referenced to 25 °C ambient.
- (2). Irms: DC current that causes the temperature rise ($\Delta T \leq 40^{\circ}\text{C}$) from 25°C ambient.

5. GENERAL SPECIFICATION

- (1). Operating temp.: -40°C ~ +125°C (Including self-generated heat).
- (2). Storage temp.: -10°C ~ +40°C R.H.:60% Max.
- (3). Moisture sensitivity level (MSL) 1
- (4). Recommended products should be used within 12 months from the date of delivery
- (5). The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

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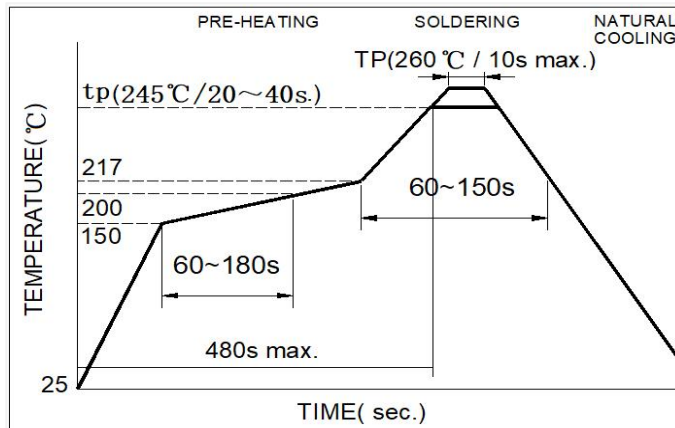


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6. SOLDERING CONDITIONS

Figure 1. Re-flow Soldering (Lead Free)



Note:

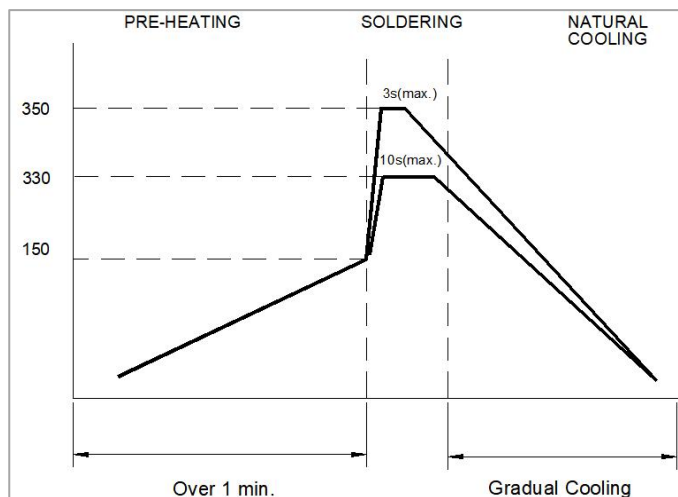
Preheat circuit and products to 150°C

260°C tip temperature (Max)

Reflow times: no more than 2 times

Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

Figure 2. Hand Soldering



Note:

Use a 20 watt soldering iron with tip diameter of 1.0mm

Limit soldering time to 3 sec.

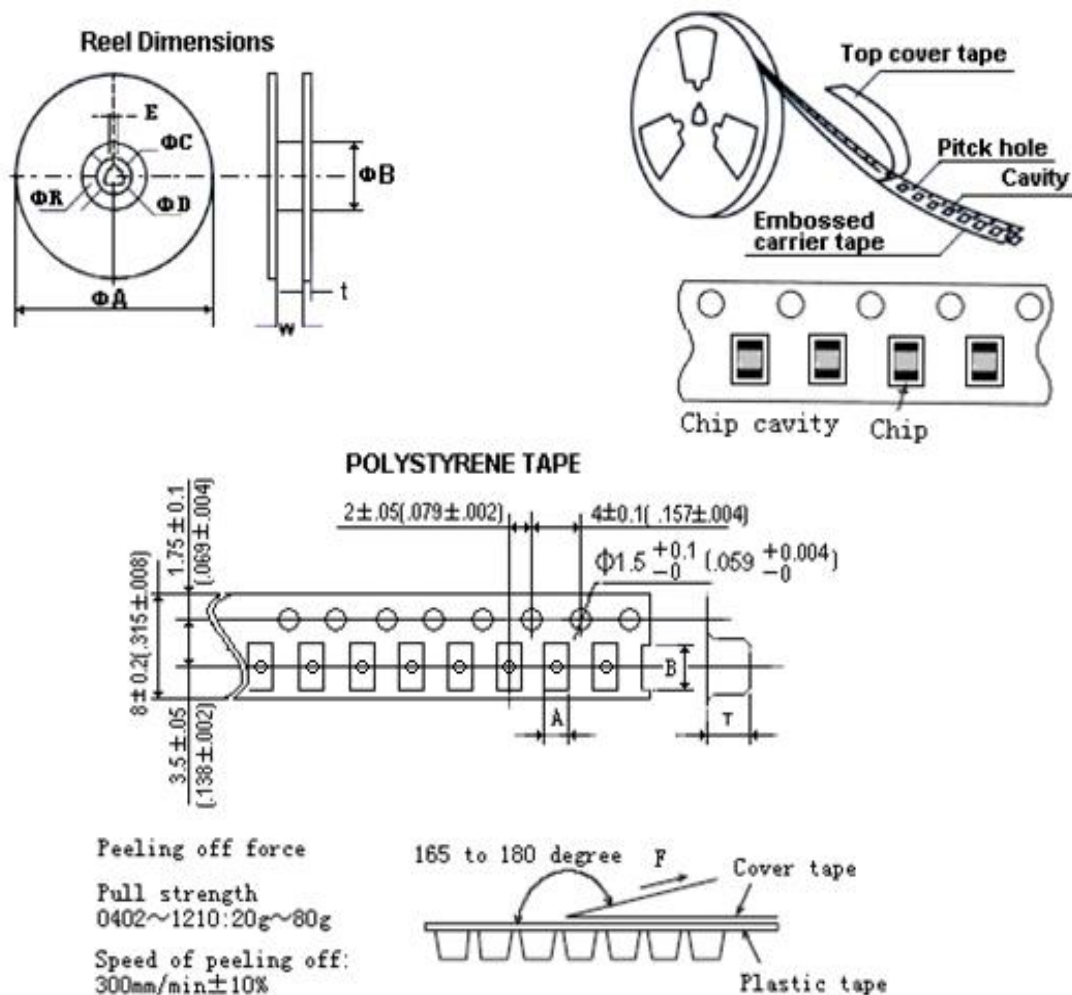
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7. PACKAGE SPECIFICATION



胶带	A	B	T
	1.95Typ.	3.6 Typ.	1.5 Typ.

Type	ΦA	ΦB	ΦC	ΦD	E	W	t
1210	178	60	13	21	2	8.4	2

包装数量(PACKAGING QUANTITY): 2000 Pcs/盘

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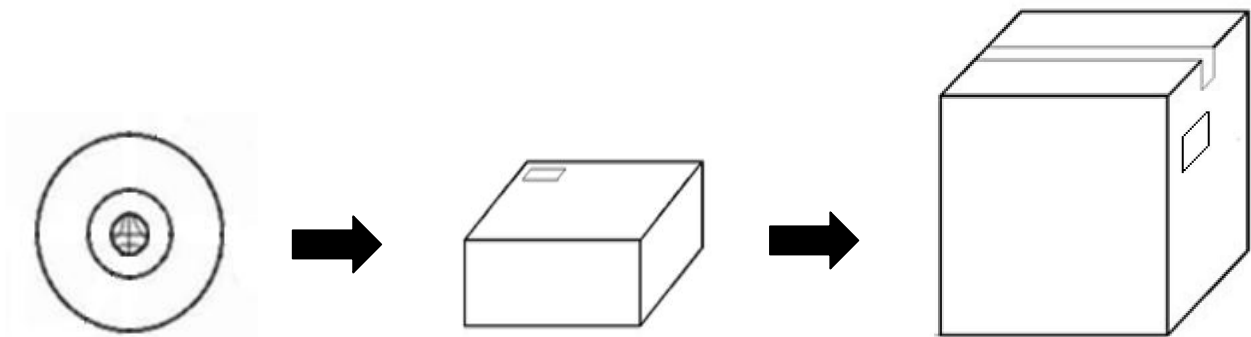


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8. Package Specifications

■Inside Box And Outside Carton



卷轴数量	→	内盒包装数量	→	外箱包装数量
每卷:2000PCS		每盒四盘，共8000 PCS		小箱6盒，共48000 PCS
				中箱8盒，共64000 PCS
				大箱10盒，共80000 PCS

内盒包装尺寸	→	外箱包装尺寸
20.3*19.3*5.5cm		小箱， 40.6*23*19.7cm
		中箱， 41*22*26cm
		大箱， 41*22*33cm

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